REMARKS

Applicants' representatives thank Examiner Talbot for the courtesies extended during the personal interview conducted on June 28, 2007. Applicants' separate record of the substance of that interview is incorporated into the following discussion.

The Examiner has maintained and repeated the rejections as set forth in the prior Office Action. Namely, claims 1-9, 13 and 17-20 were rejected under 35 USC §103(a) as being unpatentable over Chen et al. or Shiotani et al. in combination with JP 54-066966; claims 1, 3-11 and 17-20 were rejected under 35 USC §103(a) as being unpatentable over JP '640 or JP '106 in combination with JP '966; and claim 12 was rejected under 35 USC §103(a) as being unpatentable over JP '640, Chen et al., Shiotani et al or JP '106 in combination with JP '966 further in combination with Ameen et al. Each of these rejections is respectfully traversed.

In the outstanding Office Action, the Examiner still maintains that one of ordinary skill in the art would have combined the references "with the expectation of achieving a superior bond between the polyimide and the metal layers." More specifically, the Examiner still maintains this position in spite of the partial translation of JP '966 which was submitted with the prior response showing that there would have been no expectation of achieving a superior bond between a polyimide and the metal layers based upon the teachings of JP '966. The combinations of references proposed by the Examiner do not present a prima facie case of obviousness. That is, the Examiner has failed to show any motivation for one of ordinary skill in the art to combine JP

'966 with the teachings of the other references. Even if the references are combined, the resulting combination fails to teach or suggest all features of the claimed invention.

JP '966 does not teach what the Examiner asserts, namely an expectation of achieving a superior bond between the polyimide and the metal layers by performing a subsequent aging step. Quite the contrary, JP '966 teaches the opposite, particularly its Example 1 which teaches that adhesion strength was reduced by about 20% compared with that prior to heat aging. This teaching would teach away from use of heat aging in the other references applied by the Examiner.

In conclusion, the cited art does not teach or suggest forming a laminate comprising a thermoplastic polyimide in which at least one conductor layer directly adheres with at least one surface of the thermoplastic polyimide to obtain a laminate and heating the laminate so that the adhesion strength between the thermoplastic polyimide and a conductor layer is enhanced. The combinations of art proposed by the Examiner would at most teach a reduction of adhesion strength by use of the claimed heating step and therefore the combination would teach away from the claimed invention.
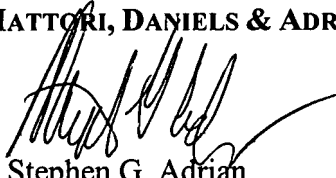
For at least the foregoing reasons, the claimed invention distinguishes over the cited art and defines patentable subject matter. Favorable reconsideration is earnestly solicited.

Should the Examiner deem that any further action by applicants would be desirable to place the application in condition for allowance, the Examiner is encouraged to telephone applicants' undersigned attorney.

Request for Reconsideration After Final Rejection
Application No. 09/782,169
Attorney Docket No. 010164

If this paper is not timely filed, Applicants respectfully petition for an appropriate

extension of time. The fees for such an extension or any other fees that may be due with respect

to this paper may be charged to Deposit Account No. 50-2866.

Respectfully submitted,

WESTERMAN, HATTORI, DANIELS & ADRIAN, LLP

Stephen G. Adrian
Attorney for Applicants
Registration No. 32,878
Telephone: (202) 822-1100
Facsimile: (202) 822-1111

SGA/arf

Attachment: Petition for Extension of Time